

Array Termination Machine



LGTM-3900 series

- Very accurate termination position
- Dipping resolution 1 micron
- Blotting function
- Anti airbubble function
- Capacity up to 50.000 pieces per hour



Array dipping of MLCC, MLCI, MLV, LTCC etc.

Array Termination Machine

Designed for dipping of array terminations on ceramic components

The dedicated design assures a flexible dipping process with a high production capacity and high quality terminations. The programmable dipping parameters allow optimization of the paste deposition and reduction of defect terminations by unique anti air bubble removal functions. Technical specification:

Paste plate:	242 x 202 x 15.6 mm
	Groove size made on request
	Plate parallelism 10 microns
Paste Box:	154 x 124 x 20 mm
HMI:	Color touch screen
	Fully programmable dipping process
Vacuum:	650mm Hg
Air pressure:	0.5 MPa
Size:	1200 x 1000 x 1950mm
Weight:	600kg

Thin Array Carrier Plates

- Superior dipping results
- Diamond shaped holes
 with ± 15micron position accuracy
- Fast heating and cooling during drying
- Lowest energy consumption
- Very low tooling cost

The unique Thin Array Carrier Plate with diamond shaped openings assures a high chip holding force with high centering accuracy. The thin carrier plate requires very low energy consumption during the drying process because of the low thickness and material choice. The drying process is therefore predominantly defined by the paste parameters.

Technical specification:

0204-0508:	1030 holes per plate
0610-0612:	704 holes per plate
	Other chip sizes on request
TACP size:	152 x 152 mm
Hole precision: ±15 microns	

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